

**ABSTRACT**

The TPS650330-Q1 EVM is an evaluation board for the TPS65033x-Q1 Power Management Integrated Circuits (PMICs). The EVM includes an onboard USB-to-I²C adapter, power terminals and jumpers for all DC regulator inputs and outputs, and test points for common measurements.

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1 Introduction

The TPS650330-Q1 device is a highly integrated PMIC for automotive camera modules. This device combines three step down converters and one low-dropout (LDO) regulator. The BUCK1 step-down converter has an input voltage range up to 18.3 V for connections to power over coax. All converters operate in a forced fixed-frequency PWM mode. The LDO can supply 300 mA and operate with an input voltage range from 2.2 V to 5.5 V. The step-down converters and the LDO have separate voltage inputs that enable maximum design and sequencing flexibility.

2 Requirements

- Computer with Windows, MacOS, or Linux operating system
- Camera PMIC GUI ([Link Here](#))
- Micro-USB Cable
- TPS650330-Q1 EVM
- DC Power Supply (4.5 V to 19 V)
 - Banana Cables for Power and GND

3 Operation Instructions

1. Ensure USB to I²C Adapter is configured properly using the jumpers mentioned in [Configuring the USB to I²C Adapter](#). For most applications, this will be the default configurations defined in the tables.
2. Configure regulator input supply rails for the expected application using the jumpers mentioned in [Regulator Input Supplies and Features](#). Take extra care not to exceed absolute maximum ratings when VSYS supplies BUCK2, BUCK3, or the LDO.
3. Connect Micro-USB to a PC capable of loading the Camera PMIC GUI.
4. Connect VSYS to a power supply capable of supporting the application and enable the supply. Typical supply voltage is 12 V. The PMIC will boot automatically as VSYS is applied.
5. Set the SEQ switch (S1) to *ON* to enable the Buck 1 and Buck 2 regulators.
6. Set GPIO switch (S4) to *ON* to enable the Buck 3 and LDO regulators.
7. Load the Camera PMIC GUI and ensure the adapter has been recognized by the PC. If the GUI says *Hardware not connected*, refer to [TPS650330-Q1 EVM Debugging](#).
8. Step 6: Once the adapter is connected, the GUI will attempt to read all registers and update the register map.

3.1 Configuring the USB to I²C Adapter

An onboard MCU acts as a USB adapter to the PMIC. This adapter allows I²C communication to the host PC as well as GPIO assertion and monitoring. By default, the onboard adapter is powered by the USB cable through an onboard dedicated 3.3 V LDO (U4). Additional configurations are allowed by reconfiguring jumpers J18 and J19, shown in [Table 3-1](#) and [Table 3-2](#). The onboard adapter must have power applied through a valid configuration.

Table 3-1. Adapter Power Source (J18)

| Selection Jumper Pin | Adapter Supply Bus |
|--|-----------------------------------|
| Pin 1 (PMIC Buck 1 Output) | Pin 2 (Adapter Input Supply Rail) |
| Pin 3 (PMIC LDO Output) | Pin 4 (Adapter Input Supply Rail) |
| Pin 5 (Dedicated 3.3 V LDO Output - <i>Default</i>) | Pin 6 (Adapter Input Supply Rail) |

Table 3-2. Dedicated LDO Supply for Adapter (J19)

| Selection Jumper Pin | Dedicated 3.3V LDO Supply Bus |
|---|--|
| Pin 1 (PMIC Buck 1 Output) | Pin 2 (Dedicated 3.3 V LDO Input Rail) |
| Pin 3 (PMIC Buck 1 Input - <i>Default</i>) | Pin 4 (Dedicated 3.3 V LDO Input Rail) |
| Pin 5 (VBUS Rail) | Pin 6 (Dedicated 3.3 V LDO Input Rail) |

The following Jumpers in [Table 3-3](#) connect the USB adapter to PMIC functional pins. These can be disconnected for flexibility.

Table 3-3. Adapter PMIC Connections

| Jumper | PMIC Pin |
|--------|----------|
| J21 | nRST |
| J22 | SEQ |

3.2 Regulator Input Supplies and Features

The four regulators on the TPS650330-Q1 EVM can be supplied with multiple supplies. The following tables show the possible supply configurations in addition to key specifications and programmable features for each regulator.

3.2.1 Buck 1 Input Supply

Table 3-4. Buck 1 Power Source (J33)

| Selection Jumper Pin | Buck1 Supply Bus |
|--------------------------------|----------------------------------|
| Pin 1 (VSYS - <i>Default</i>) | Pin 2 (Buck 1 Input Supply Rail) |

3.2.2 Mid-Vin Buck1 Features

Table 3-5. Mid-Vin (Buck1) Features

| Feature | Specification |
|-------------------------------|------------------------------|
| Input Voltage Range | 4 V to 18.3 V |
| Operating Current | Maximum of 1.5 A |
| Current Limiting | 1.8 A to 3.6 A |
| Status Monitoring | UVLO, UV, HOT, OVP, SCG, OCP |
| Over-Voltage Protection (OVP) | VOUT = 109% to 115% |
| Short-Circuit Threshold (SCG) | VOUT = 250 mV to 350 mV |

Table 3-6. Mid-Vin (Buck1) Configurable Settings

| Feature | Configurable Range |
|-----------------------------|-------------------------------------|
| Output Voltage | 2.5 V to 4.0 V |
| PVIN_B1 UVLO Rising | 3.64 V to 9.36 V |
| PVIN_B1 UVLO Falling | 3.5 V to 9 V |
| Output Discharge | Disabled, 125 Ω, 250 Ω, and 500 Ω |
| Sequencing | Enable, Dependencies, and Fault RST |
| Sequence Delay (Off and On) | 0 ms to 20 ms |

Note: Over-voltage monitor settings are available for the TPS650331-Q1, TPS650332-Q1, and TPS650333-Q1.

3.2.3 Buck 2 Input Supply

Table 3-7. Buck 2 Power Source (J15)

| Selection Jumper Pin | Buck2 Supply Bus |
|---|----------------------------------|
| Pin 1 (VSYS) | Pin 2 (Buck 2 Input Supply Rail) |
| Pin 3 (Buck1 Output Rail - <i>Default</i>) | Pin 4 (Buck 2 Input Supply Rail) |

3.2.4 Buck 3 Input Supply

Table 3-8. Buck 3 Power Source (J16)

| Selection Jumper Pin | Buck3 Supply Bus |
|---|----------------------------------|
| Pin 1 (VSYS) | Pin 2 (Buck 3 Input Supply Rail) |
| Pin 3 (Buck1 Output Rail - <i>Default</i>) | Pin 4 (Buck 3 Input Supply Rail) |

3.2.5 Low-Vin Buck2 and Buck3 Features

Table 3-9. Low-Vin (Buck2 and Buck3) Features

| Feature | Specification |
|-------------------------------|-------------------------|
| Input Voltage Range | 2.5 V to 5.5 V |
| Operating Current | Maximum of 1.2 A |
| Current Limiting | 1.6 A to 2.8 A |
| Status Monitoring | UV, HOT, OVP, SCG, OCP |
| Over-Voltage Protection (OVP) | VOUT = 109% to 115% |
| Short-Circuit Threshold (SCG) | VOUT = 250 mV to 350 mV |

Table 3-10. Low-Vin (Buck2 and Buck3) Configurable Settings

| Feature | Configurable Range |
|-----------------------------|-------------------------------------|
| Output Voltage | 0.9 V to 1.9 V |
| Under-Voltage Flags (UV) | VOUT = 94.5%, 95%, 95.5%, and 96% |
| Spread Spectrum | Enable or Disable |
| Sequencing | Enable, Dependencies, and Fault RST |
| Sequence Delay (Off and On) | 0 ms to 20 ms |

Note: Over-voltage monitor settings are available for the TPS650331-Q1, TPS650332-Q1, and TPS650333-Q1.

3.2.6 LDO Input Supply

Table 3-11. PMIC LDO Power Source (J8)

| Selection Jumper Pin | PMIC LDO Supply Bus |
|---|------------------------------------|
| Pin 1 (VSYS) | Pin 2 (PMIC LDO Input Supply Rail) |
| Pin 3 (Buck1 Output Rail - <i>Default</i>) | Pin 4 (PMIC LDO Input Supply Rail) |
| Pin 5 (Buck2 Output Rail) | Pin 6 (PMIC LDO Input Supply Rail) |
| Pin 7 (Buck3 Output Rail) | Pin 8 (PMIC LDO Input Supply Rail) |

3.2.7 Low Noise LDO Features

Table 3-12. Low Noise LDO Features

| Feature | Specification |
|-------------------------------|-----------------------------|
| Input Voltage Range | 2.5 V to 5.5 V |
| Operating Current | Maximum of 150 mA or 300 mA |
| Current Limiting | Minimum of 200 mA or 400 mA |
| Status Monitoring | UV, HOT, OVP, SCG, OCP |
| Over-Voltage Protection (OVP) | VOUT = 109% to 115% |
| Short-Circuit Threshold (SCG) | VOUT = 250 mV to 350 mV |

Table 3-13. Low Noise LDO Configurable Settings

| Feature | Configurable Range |
|-----------------------------|-------------------------------------|
| Output Voltage | 1.8 V, or 2.7 V to 3.3 V |
| Under-Voltage Flags (UV) | VOUT = 94.5%, 95%, 95.5%, and 96% |
| Load Switch Mode | Enable or Disable |
| Current Limit | 200 mA, 400 mA |
| Sequencing | Enable, Dependencies, and Fault RST |
| Sequence Delay (Off and On) | 0 ms to 20 ms |

Note: Over-voltage flag settings are available for the TPS650331-Q1, TPS650332-Q1, and TPS650333-Q1.

3.3 Selecting the Logic Supply Voltage

Table 3-14. VIO Power Source (J8)

| Selection Jumper Pin | VIO Supply Bus |
|---|--------------------------------|
| Pin 1 (Buck1 Output Rail - <i>Default</i>) | Pin 2 (VIO Input Supply Rail) |
| Pin 3 (Buck2 Output Rail) | Pin 4 (VIO Input Supply Rail) |
| Pin 5 (Buck3 Output Rail) | Pin 6 (VIO Input Supply Rail) |
| Pin 7 (PMIC LDO Output Rail) | Pin 8 (VIO Input Supply Rail) |
| Pin 9 (Dedicated 3.3 V LDO) | Pin 10 (VIO Input Supply Rail) |

4 EVM Configurations

The following sections outline how to configure the TPS650330-Q1 EVM for general experimentation.

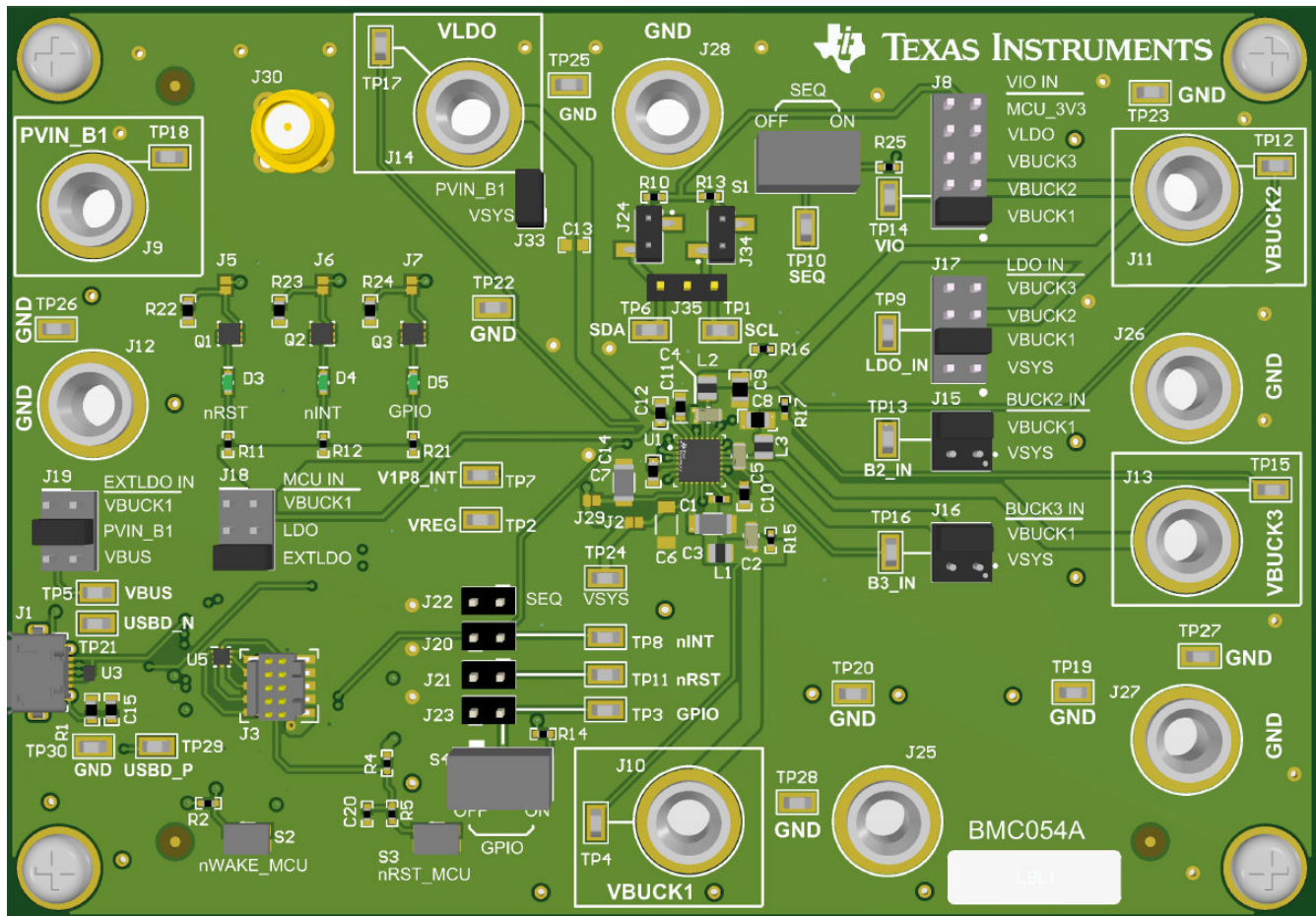


Figure 4-1. TPS650330-Q1 EVM Top View

5 Test Points

5.1 Voltage Test Points

The TPS650330-Q1 EVM contains 30 test points for various measurements. Trace assignments to the test points are shown in [Table 5-1](#). For reference, [Figure 5-1](#) demonstrates the test point locations on the EVM.

Table 5-1. TPS650330-Q1 EVM Test Points

| Test Point Number | Associated Trace |
|-------------------|------------------|
| TP1 | SCL |
| TP2 | VREG |
| TP3 | GPIO |
| TP4 | Buck 1 Output |
| TP5 | VBUS |
| TP6 | SDA |
| TP7 | V1P8_INT |
| TP8 | nINT |
| TP9 | PMIC LDO Input |
| TP10 | SEQ |
| TP11 | nRSTOUT |
| TP12 | Buck 2 Output |
| TP13 | Buck 2 Input |
| TP14 | VIO |
| TP15 | Buck 3 Output |
| TP16 | Buck 3 Input |
| TP17 | PMIC LDO Output |
| TP18 | Buck 1 Input |
| TP19 | GND |
| TP20 | GND |
| TP21 | USB_D_N |
| TP22 | GND |
| TP23 | GND |
| TP24 | VSYS |
| TP25 | GND |
| TP26 | GND |
| TP27 | GND |
| TP28 | GND |
| TP29 | USB_D_P |
| TP30 | GND |

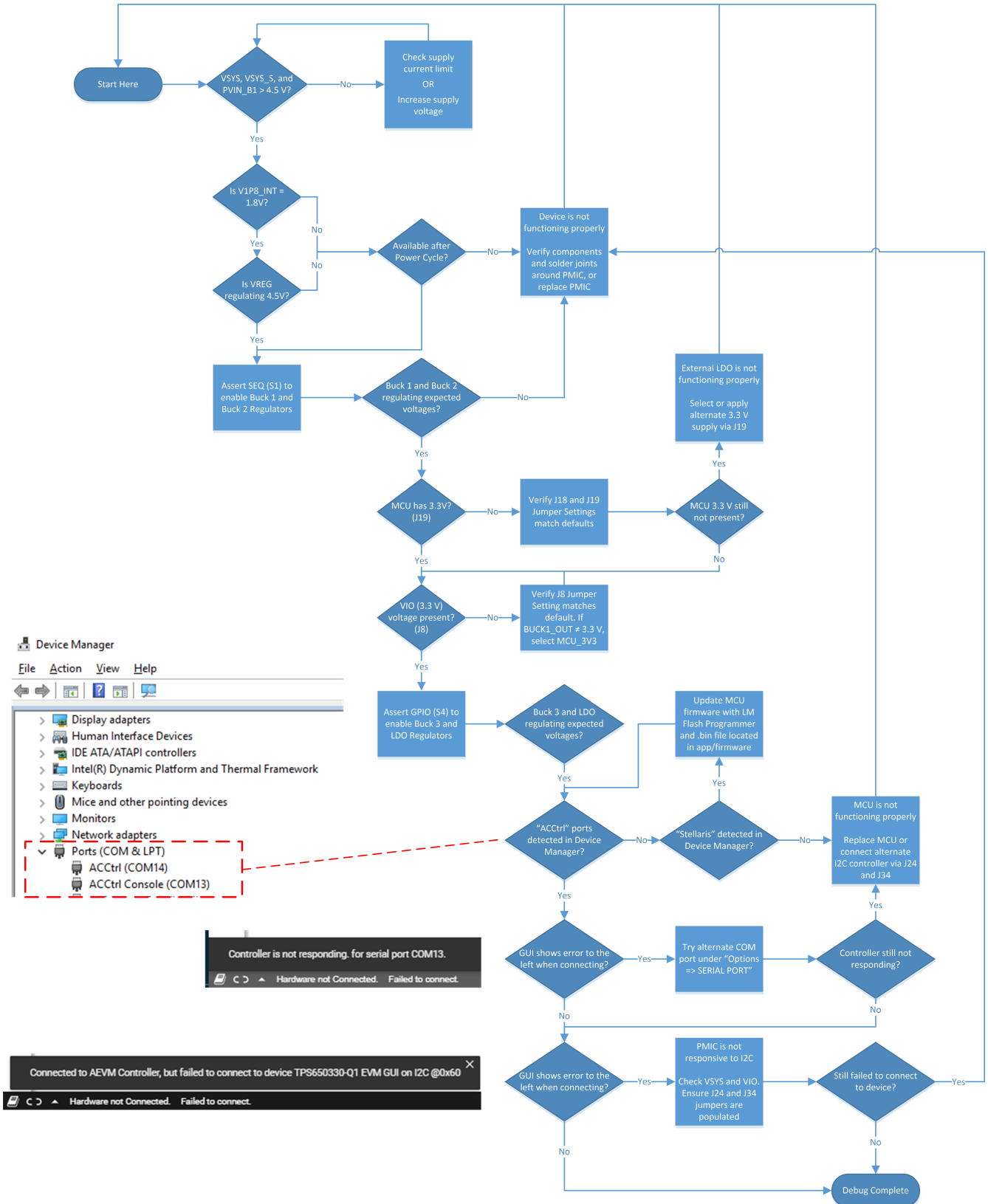


Figure 6-1. TPS650330-Q1 EVM Debugging Flow Chart

6.1.1 I²C Communication Port and Adapter Debugging

By default, the GUI will recognize two serial ports from the EVM adapter, but may not select the I²C bridge automatically. Once the EVM is powered and the USB cable is connected to the computer, click the connect icon at the bottom left of the GUI. If the bottom notification updates to *Hardware Not Selected*:

1. Click the Options menu at the top of the GUI, select *Serial Port*.

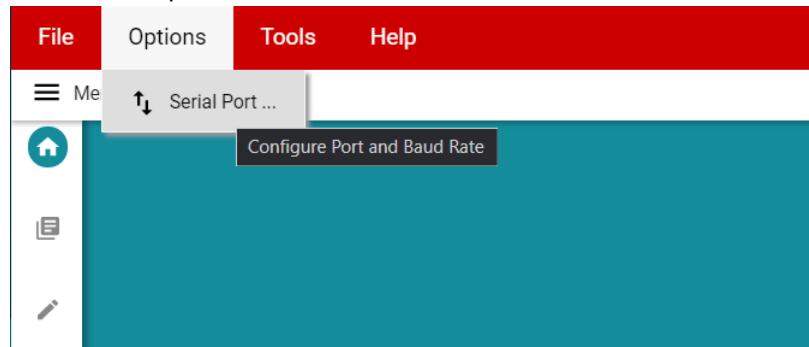


Figure 6-2. Opening Serial Port Options

2. Use the Ports dropdown to select the alternative interface.

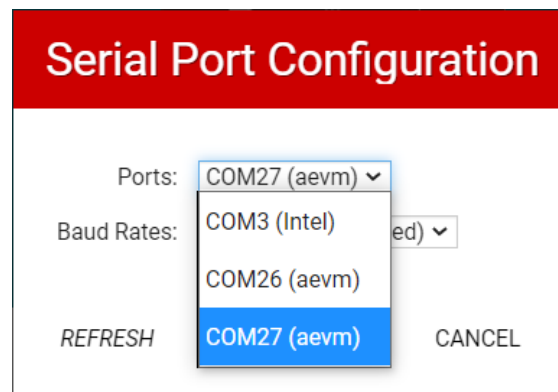


Figure 6-3. Selecting an Alternate Port

After clicking OK, the GUI should connect to the device properly. If communication to the EVM is lost, most issues can be resolved by pressing the nRST_MCU button (S3) on the EVM. Afterwards, further issues can be diagnosed by confirming that MCU_IN (J18) is still present, and that the I²C pull-up domain is still active.

6.1.2 Updating MCU Firmware

If the EVM on-board MCU is showing up under the Device Manager with a *Stellaris...* title, the MCU firmware needs to be updated to communicate with the GUI. One way to do this is with TI's free [LM Flash Programmer](#) tool. Once the firmware is updated, the MCU should show up as *ACCtrl...* COM ports in the Device Manager.

1. Download the GUI source files from the Gallery. The EVM firmware is the .bin file located in the install_image_TPS6503xx-Q1_GUI/TPS6503xx-Q1_GUI/app/firmware folder.
2. Open LM Flash Programmer with the EVM connected through USB.
3. Select *USB DFU* in the *Configuration* tab. The Stellaris device should show in the device list box after refreshing.
4. Select the *Program* tab.
5. Browse to the .bin file downloaded from the GUI.
6. Leave all other settings as default.
7. Click *Program*.

6.2 Navigating the GUI

The GUI contains the following five sections, selectable on the left side of the GUI or by clicking the Menu tab in the top left corner.

- Home
- Block Diagram
- Registers
- Device Configuration
- Re-Program PMIC

6.2.1 Home

The Home section is the landing page of the GUI. Here the GUI presents an overview of the EVM and [Programming BoosterPack \(BOOSTXL-TPS65033\)](#), and emphasize navigation to the remaining four sections through the tiles on the bottom of the page.

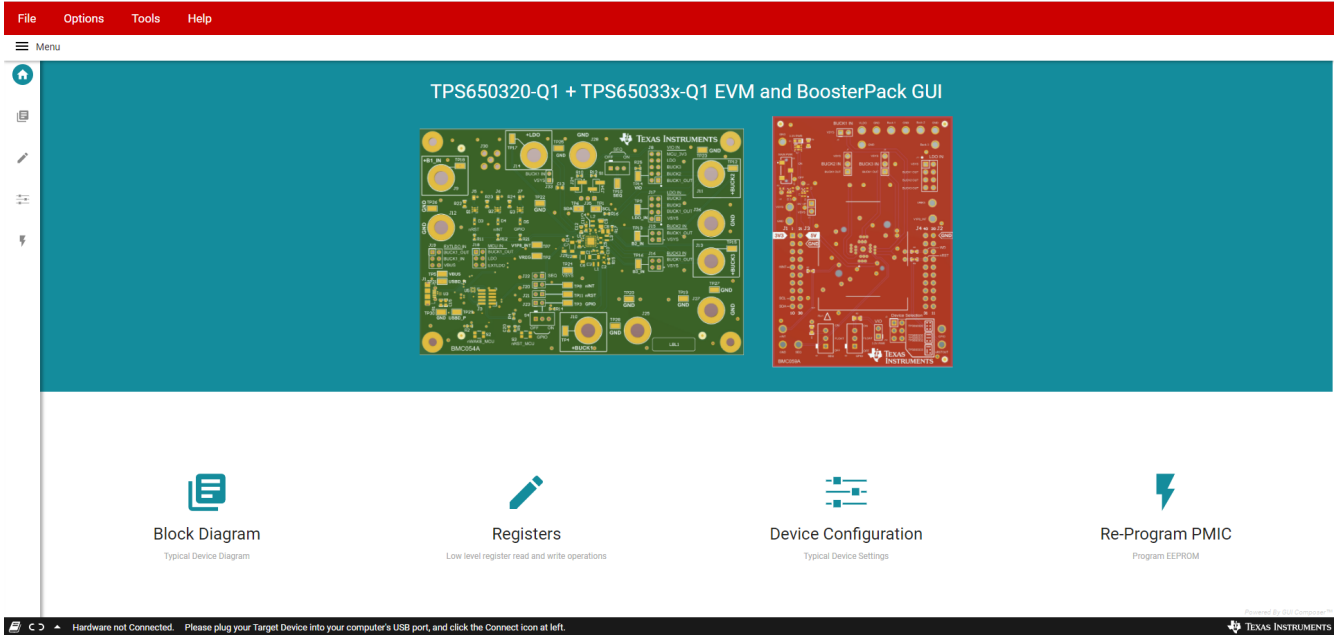


Figure 6-4. TPS6503xx-Q1 GUI Home Screen

6.2.2 Block Diagram

The Block Diagram section displays the typical components and functional blocks of the PMIC. A block diagram for the [Programming BoosterPack](#) is also shown.

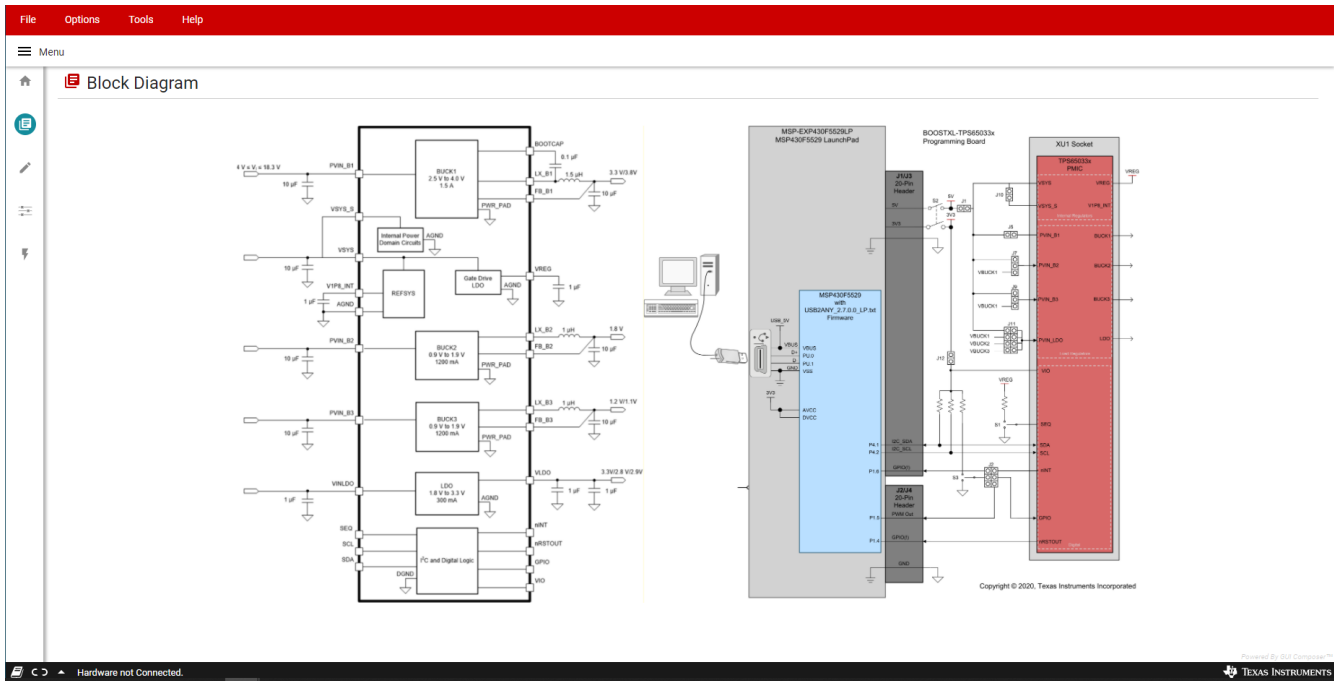


Figure 6-5. TPS6503xx-Q1 GUI Block Diagram Page

6.2.3 Registers

The Registers section provides an overview of the internal register map, and includes basic interfaces for each PMIC register. Figure 6-6 illustrates the register page and the primary interactive regions.

| Register Name | Address | Value | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|----------------|---------|-------|---|---|---|---|---|---|---|---|
| USER REGISTERS | | | | | | | | | | |
| PID | 0x00 | 0x00 | 0 | 0 | 0 | | | | | |
| RID | 0x01 | 0x00 | 0 | 0 | 0 | | | | | |
| CONTROL_LOCK | 0x02 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| BUCK_LDO_CTRL | 0x03 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| GPIO_CTRL | 0x04 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| CONFIG_LOCK | 0x05 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| LDO_GPIO_CFG | 0x06 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| BUCK1_VOUT | 0x07 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| BUCK1_UVLO | 0x08 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| BUCK2_VOUT | 0x09 | 0x00 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |

Figure 6-6. Register Page Interfaces

The register table displays each register name, address, last known value from the PMIC, and corresponding bit values. Selecting a title or bit fields in the table will update the Field View column on the right side of the GUI. The Field View displays the individual fields contained within the associated register address. Within the register page, clicking a blue icon containing a question mark (?) will expand additional descriptions if available. The expanded description views can then be closed by clicking the red (x) icon.

This register page can poll the device periodically using the *Auto Read* feature in the top right corner, or allow manual read instructions using the *Read Register* and *Read All Registers*.

A drop-down menu selection at the top right of the register map indicates how the registers are written as the user interacts with the register page. With *Immediate* selected, any update to the register page is automatically sent to the PMIC, whereas *Deferred* will wait for the *Write Register* or *Write All Registers* instructions before communicating with the device. After each write, the register page will automatically read the affected register address to confirm the latest value in the device.

6.2.4 Device Configuration

The Device Configuration section is organized into selectable tabs at the top of the page, where only the contents of the blue tab is actively displayed. Each tab contains categorized visual instruments relating to individual bit fields within the register map. Each instrument is linked to the latest bit values in the register map table, and can be used to alter settings within the PMIC through the dropdown menus or check box features. If the *Auto Read* function in the register map is inactive, the *Read All Registers* button in the top right area of the Device Configuration page can be used to manually refresh the register page, which will then update the instruments with the latest device values.

The PMIC incorporates *Control Lock* and *Configuration Lock* features that can prevent I²C writes to various registers within the device. The status of these locks will always be displayed in the top right hand corner of the Device Configurations page, and can be toggled by clicking their associated checkbox. When the GUI is properly connected to the EVM and write instructions appear to be ignored by the PMIC, confirm the status of these indicators to verify the device is able to accept new write instructions.

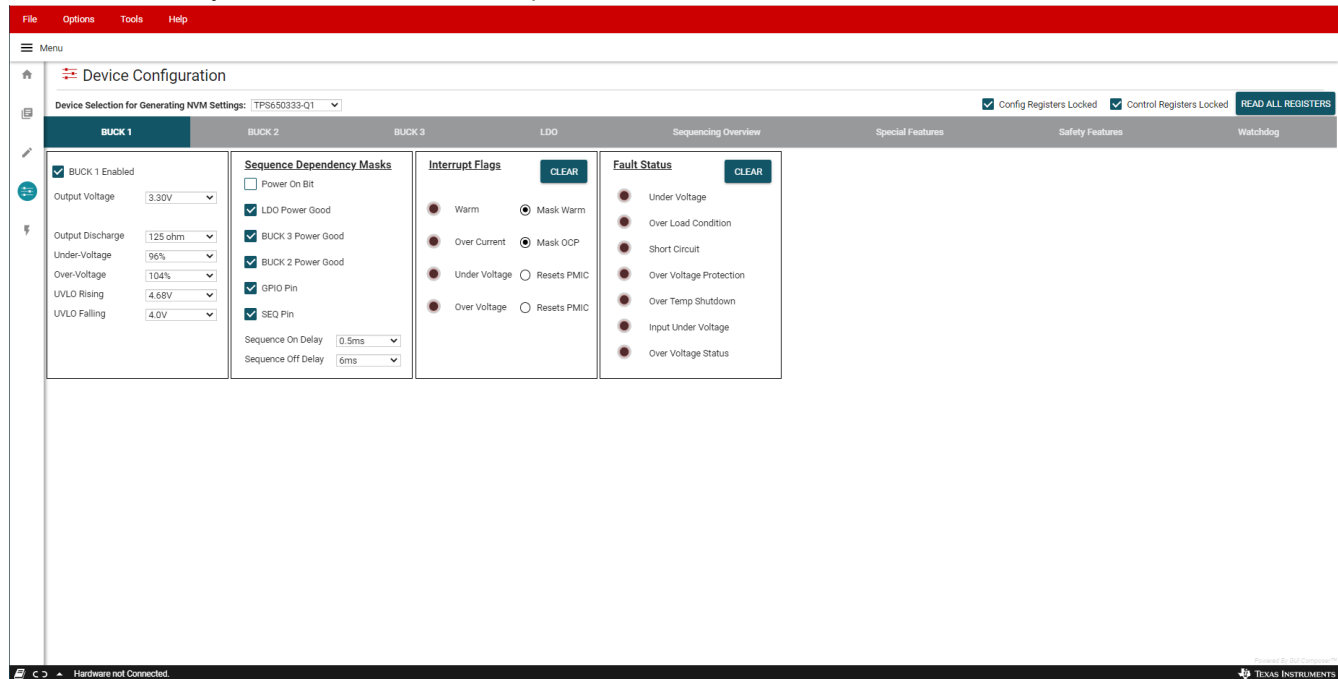


Figure 6-7. TPS6503xx-Q1 GUI Device Configuration Page

6.2.4.1 Using Device Configuration to Define Spin Settings

In some circumstances, TI may provide customized, pre-programmed devices for the camera application. Contact a local TI sales representative for more information.

The Device Configuration tabs in the GUI can be used to define custom settings for TI to pre-program into the device Non-Volatile Memory (NVM). Before beginning the spin definition, see the [Camera PMIC Spin Selection Guide](#) to determine if there is an existing spin that is already compatible with the target application and the image sensor or both.

Since the visual instruments in the Device Configuration page link directly to the corresponding bits and registers in the Register Map page, the Device Configuration page can be used to quickly define desired OTP register settings.

1. Select the desired camera PMIC from the drop-down menu above the tab indicators to start. The GUI will automatically show, hide, or disable features corresponding to the selected PMIC. This drop down box will not be adjustable if a device is connected to the GUI.

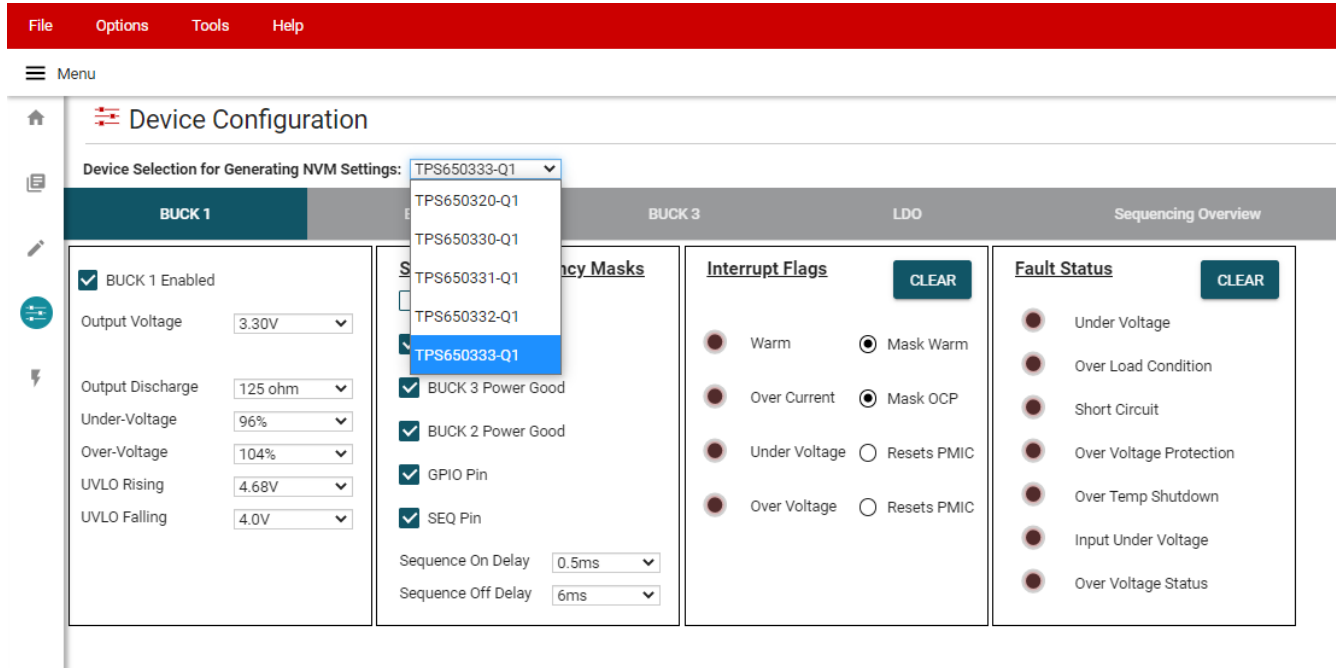


Figure 6-8. Device Selection for Generating NVM Settings

2. Select the desired regulator, sequencing, and additional feature settings in each of the tabs. These changes will be reflected in the Register Map page. For determining the power sequence settings, see [Section 6.2.4.2](#).
3. Click File > Save Settings in the top left corner of the GUI. This exports the register settings in a JSON file that is provided to generate the NVM spin.

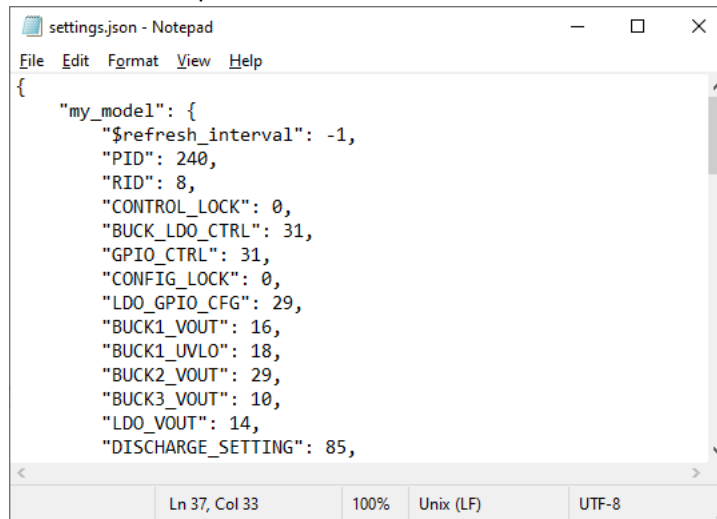


Figure 6-9. Example Settings Output

6.2.4.2 Configuring the Power Sequence

The *Sequencing Overview* tab includes instruments to customize the power sequence of the PMIC. Note that the check boxes are power sequence *masks*. If a particular logic signal needs to be included as part of the regulator or logic power up sequence, leave the box next to the logic signal unchecked. TI recommends to set *Power On Bit* unmasked for each rail that is required in the application.

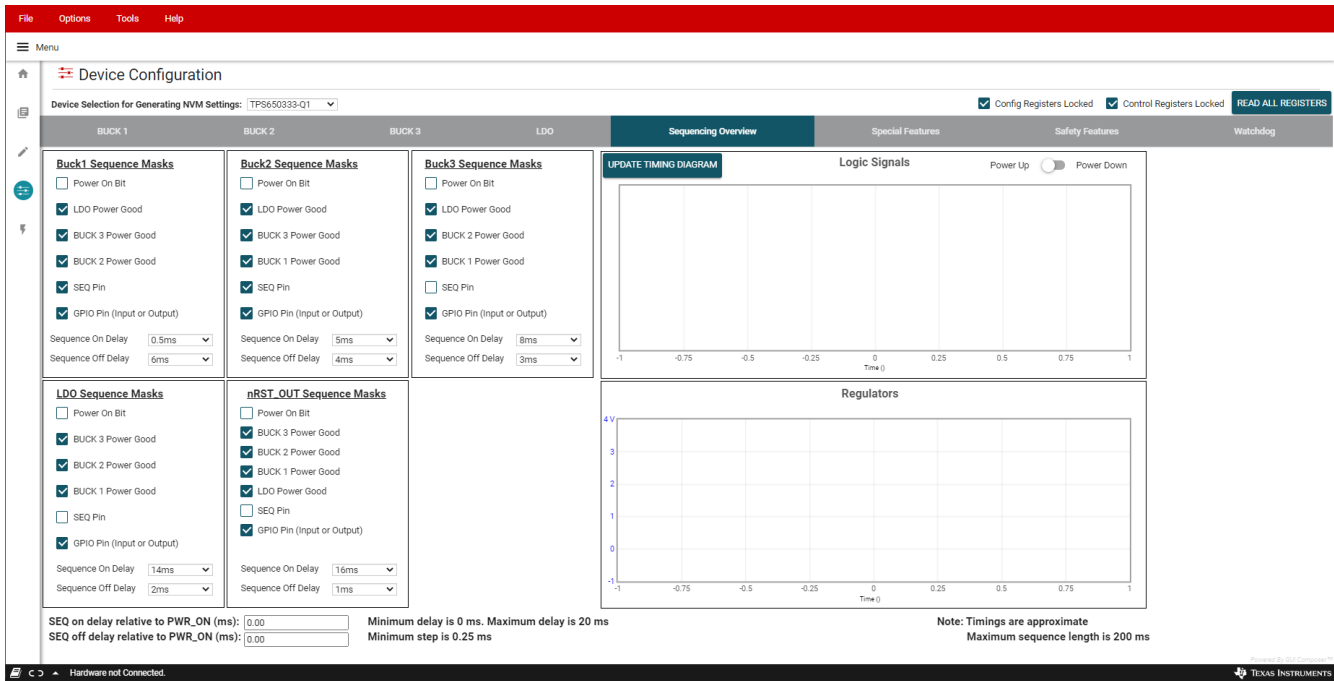


Figure 6-10. Sequencing Overview Tab

When using a TPS65033x-Q1 device, the GPIO pin can also be used for power sequencing of an external regulator or other device. In the *Special Features* tab, configure GPIO as an output to include its sequencing in the *Sequencing Overview* tab. Note that when using GPIO for sequencing, the GPIO Function must be *Enabled*.

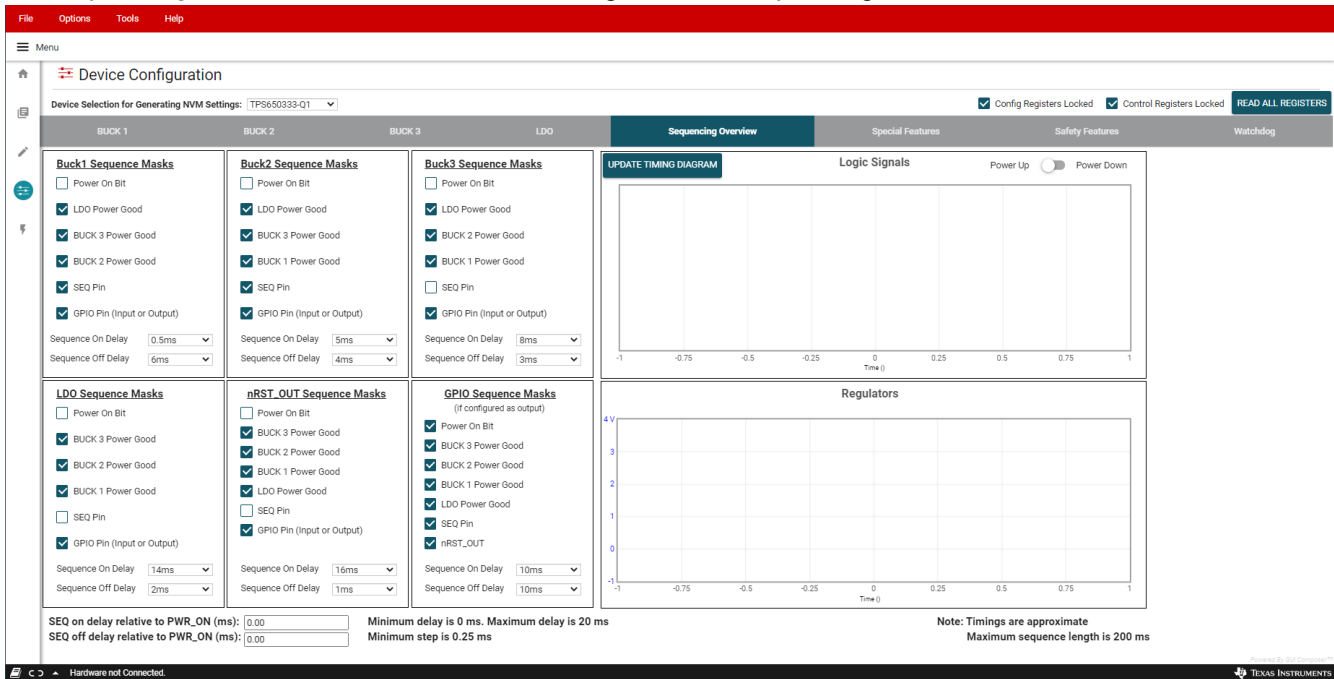


Figure 6-11. Sequencing Overview Including GPIO

For reference, the GUI can generate example power-up and power-down timing diagrams based on the sequence settings present when the *UPDATE TIMING DIAGRAM* button is clicked. As noted, rise and fall times are approximate, and the maximum sequence length is 200 ms. Changes to regulator enable and output discharge settings are reflected in the timing diagram. If the sequence settings are not valid, the GUI will provide a notifying message and the timing diagram will not be updated. For example, if a regulator is enabled but fails to power-up within 200 ms, the sequence settings are not valid.

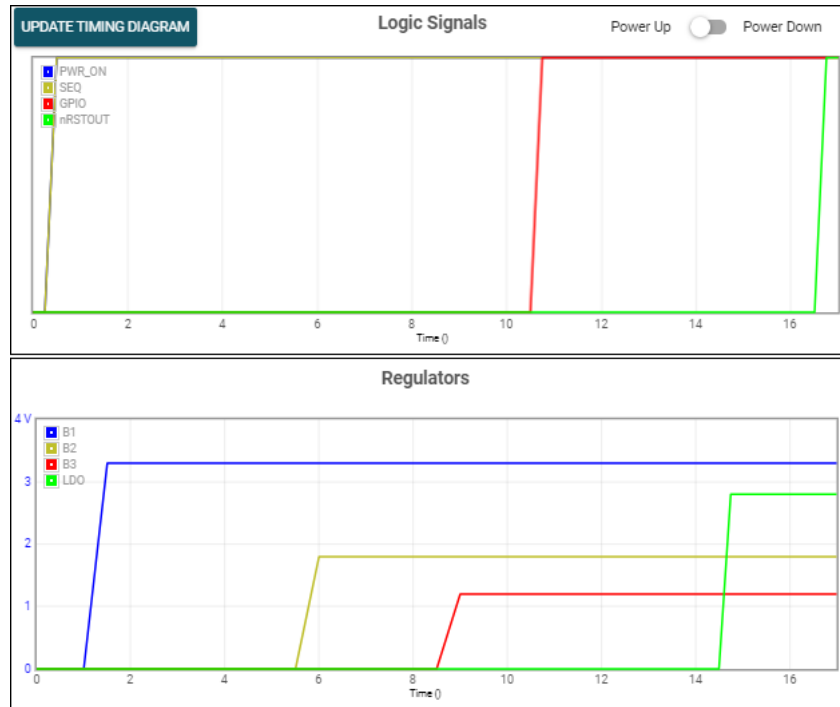


Figure 6-12. GUI Generated Timing Diagram

6.2.5 Re-Program PMIC

The Re-Program PMIC section contains a button for sending the EEPROM Program Command to the device. After the EEPROM Program Command is sent, the device will store the existing register configurations permanently and the PMIC will automatically restart with the latest settings. The device can be re-programmed multiple times to evaluate various configurations.



Figure 6-13. TPS6503xx-Q1 GUI Re-Program PMIC Page

6.3 In-Circuit Programming

The TPS650330-Q1 EVM demonstrates the in-circuit programming capabilities of the TPS650330-Q1 PMIC in a typical application. This section provides an example in-circuit programming procedure with application considerations.

1. Verify the desired power and sequence settings using the GUI's Sequencing Overview tools. See [Configuring the Power Sequence](#).
2. Validate the settings with the [BOOSTXL-TPS65033](#). This socketed board provides a quicker way to evaluate device settings.
3. Once settings are verified and validated, configure the TPS650330-Q1 EVM for a typical camera application:
 - a. Ensure the I2C pull-up jumpers (J24 and J34) are populated.
 - b. Supply the PMIC VIO with either the Buck 1 or Buck 2 output. See [Selecting the Logic Supply Voltage](#).
 - c. Tie the PMIC Buck 1 input to VSYS. See [Buck 1 Input Supply](#).
 - d. Supply the PMIC Buck 2, Buck 3, and LDO with the Buck 1 output. See [Selecting Regulator Input Supplies](#).
4. Assert SEQ (S1) before applying power.
5. Apply a Buck 1 input voltage (typical is 12 V) to power up the device. By default, the Buck 1 and Buck 2 regulators are enabled, allowing the 3.3 V and 1.8 V rails to power up.
 - a. In a typical camera application, this may be sufficient to power up the serializer and enable PMIC programming over the Serializer-Deserializer (SerDes) back-channel.
 - b. If additional rails are required, assert GPIO (S4) to enable the Buck 3 and LDO regulators.
6. Unlock the configuration and control registers.
7. Re-program the PMIC settings. If changing a regulator output voltage, TI recommends disabling the regulator first. If doing this in an application setting shuts down a critical component, change the output voltage in small steps to prevent triggering under or over-voltage fault handling.
8. If the device configuration Cyclic Redundancy Check (CRC) is enabled, calculate and write the new configuration CRC by running the GUI's built-in script. For more information on the GUI's capabilities for programming automation, see the [BOOSTXL-TPS65033 User's Guide](#).

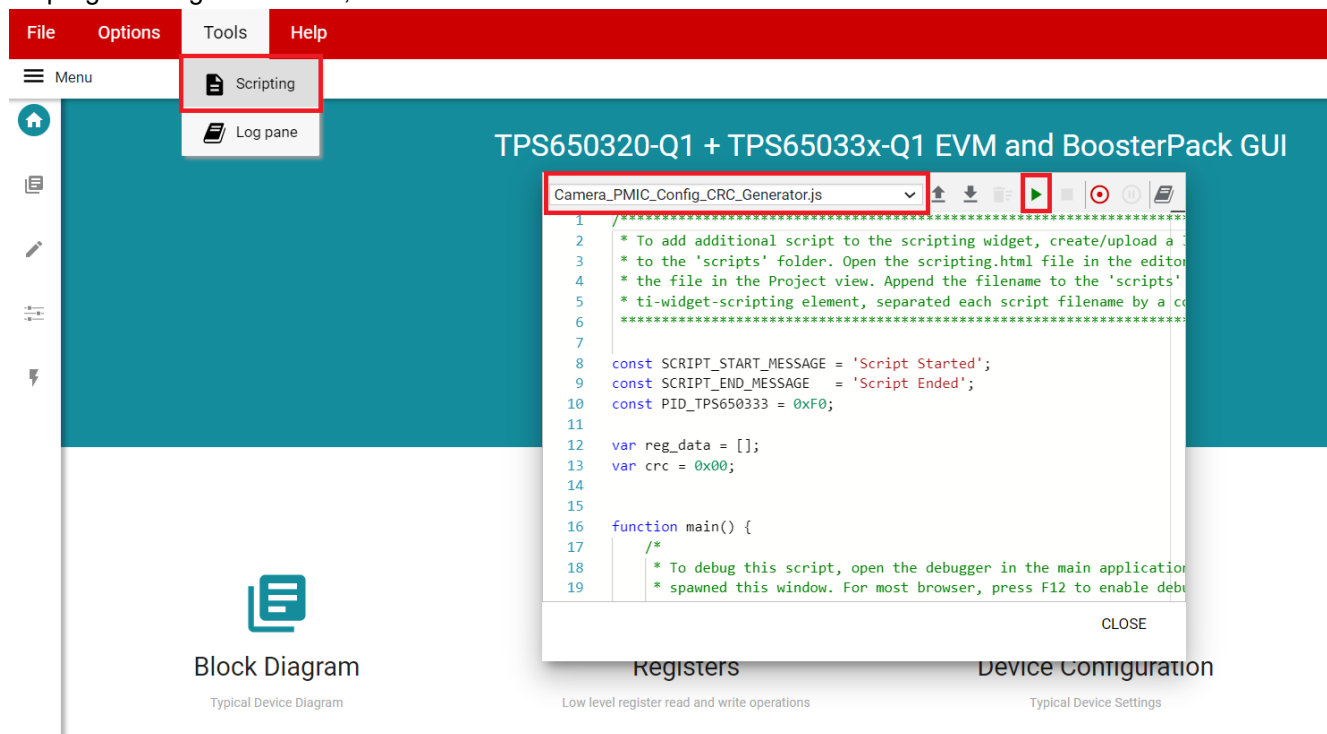


Figure 6-14. GUI Configuration CRC Script

9. Burn the final PMIC register settings to EEPROM.
10. Validate the settings on subsequent startups.

7 Typical Performance Plots

7.1 Power Sequence Plots

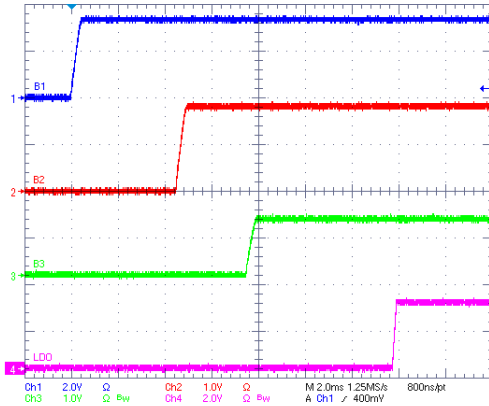


Figure 7-1. TPS650330-Q1 Default Power Up Sequence

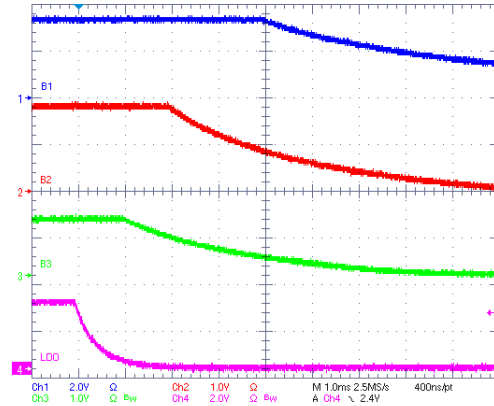
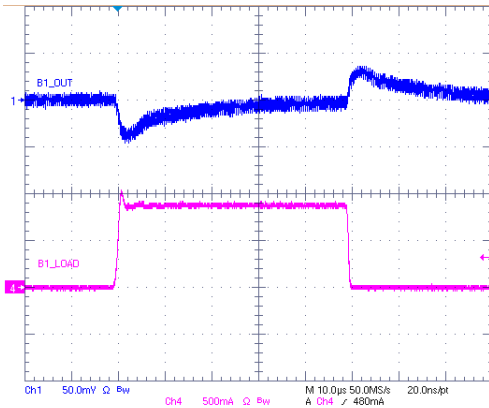


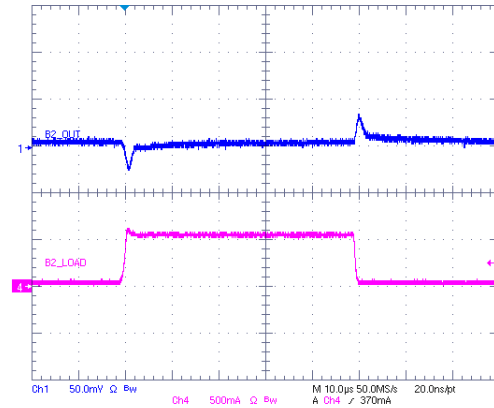
Figure 7-2. TPS650330-Q1 Default Power Down Sequence

7.2 Load Transient Plots



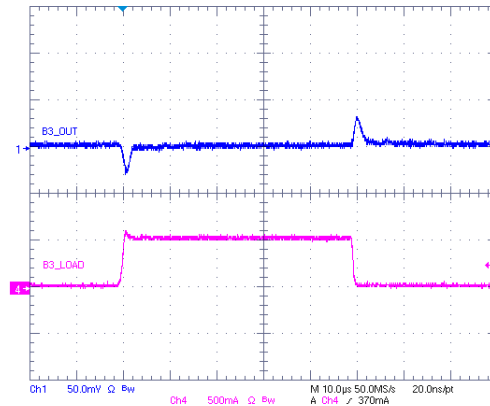
VIN = 12 V VOUT = 3.3 V IOU = 1 mA to 750 mA in 1 µs

Figure 7-3. Buck 1 Load Transient



VIN = 3.3 V VOUT = 1.8 V IOU = 1 mA to 300 mA in 1 µs

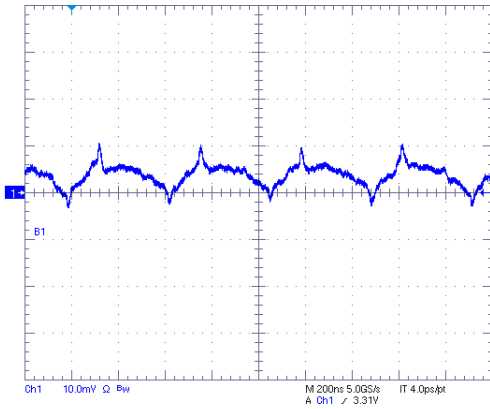
Figure 7-4. Buck 2 Load Transient



VIN = 3.3 V VOUT = 1.2 V IOU = 1 mA to 300 mA in 1 µs

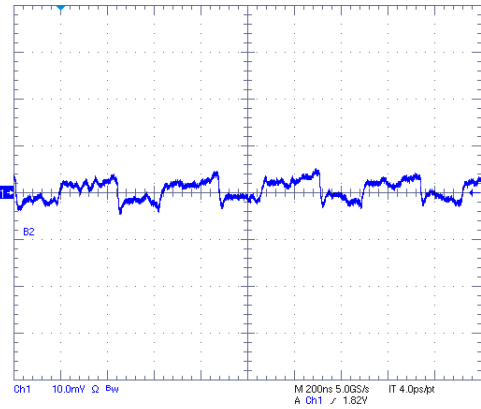
Figure 7-5. Buck 3 Load Transient

7.3 Output Voltage Ripple Plots



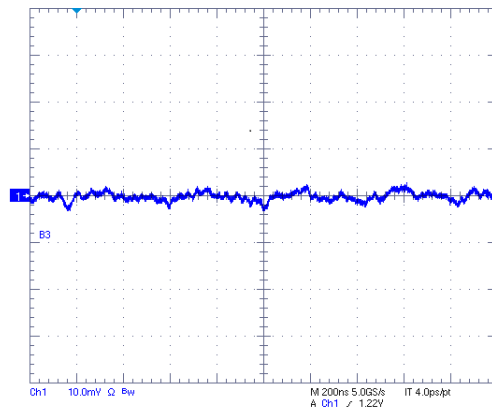
VIN = 12 V VOUT = 3.3 V IOUT = 750 mA

Figure 7-6. Buck 1 Output Voltage Ripple



VIN = 3.3 V VOUT = 1.8 V IOUT = 600 mA

Figure 7-7. Buck 2 Output Voltage Ripple



VIN = 3.3 V VOUT = 1.2 V IOUT = 600 mA

Figure 7-8. Buck 3 Output Voltage Ripple

7.4 Efficiency Plots

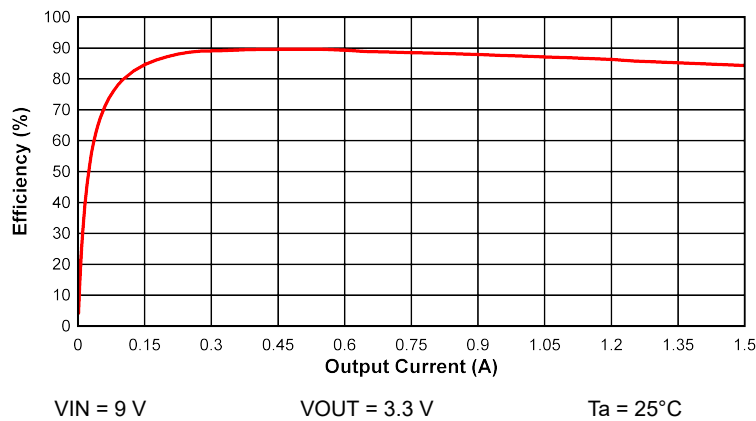


Figure 7-9. Buck 1 Efficiency Curve

7.4 Efficiency Plots

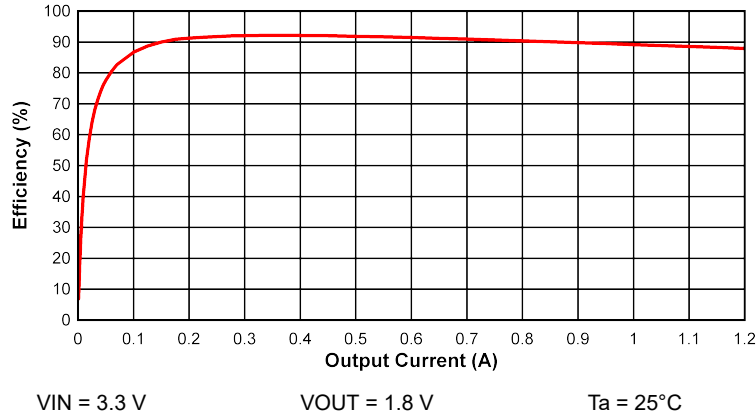


Figure 7-10. Buck 2 Efficiency Curve

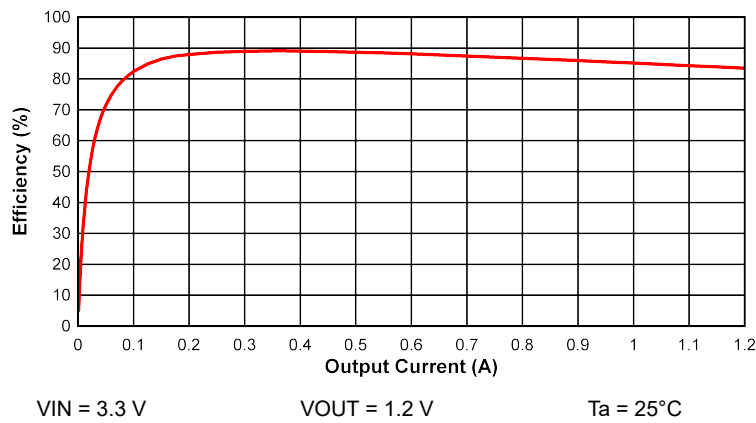


Figure 7-11. Buck 3 Efficiency Curve

7.5 LDO Output Noise

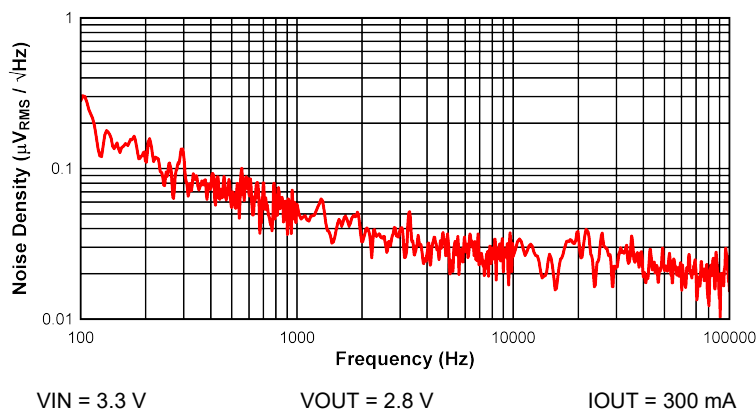


Figure 7-12. LDO Output Noise Density

8 TPS650330-Q1 EVM Schematic

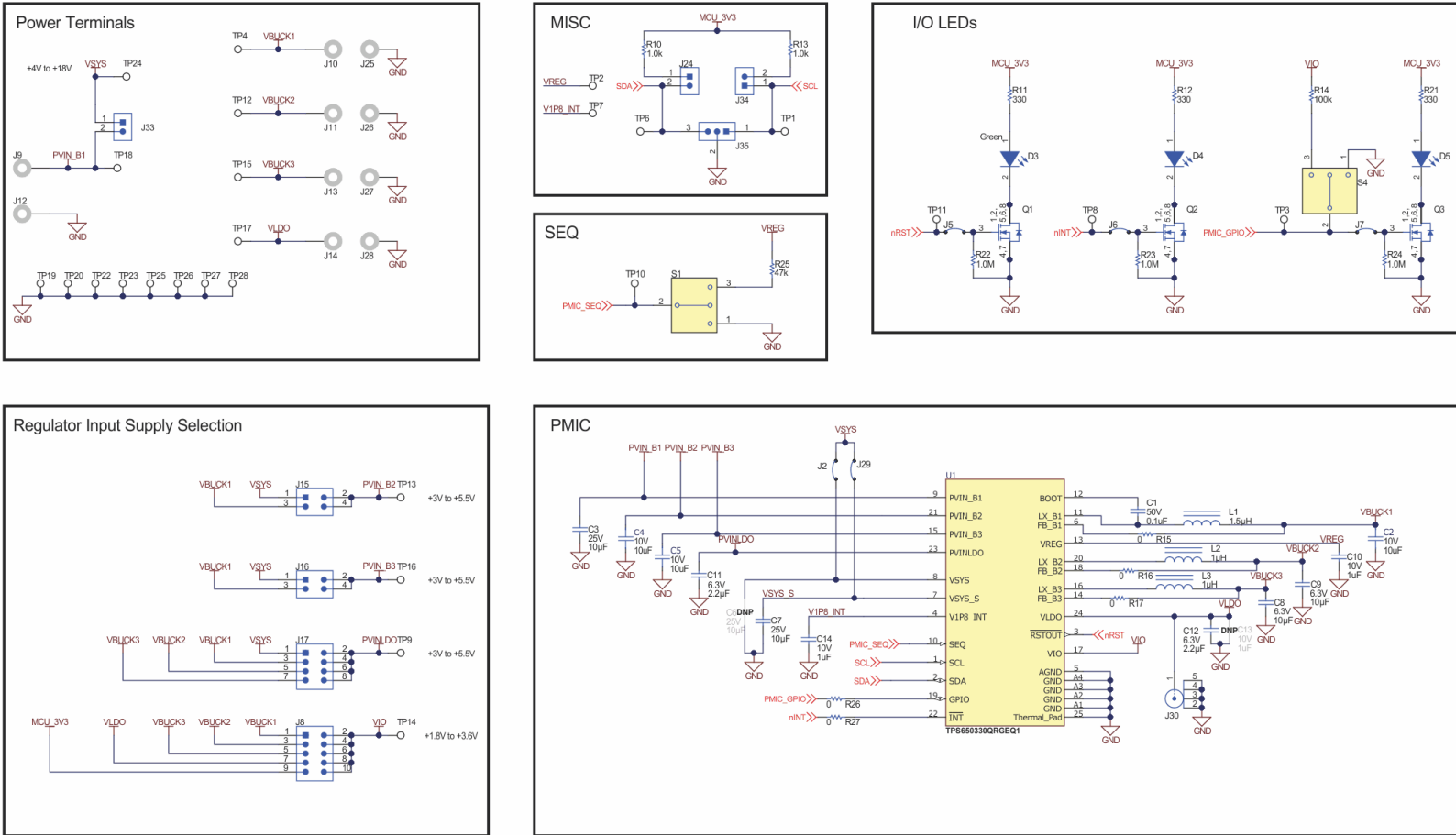


Figure 8-1. TPS650330-Q1 Schematic

TPS650330-Q1 EVM Schematic

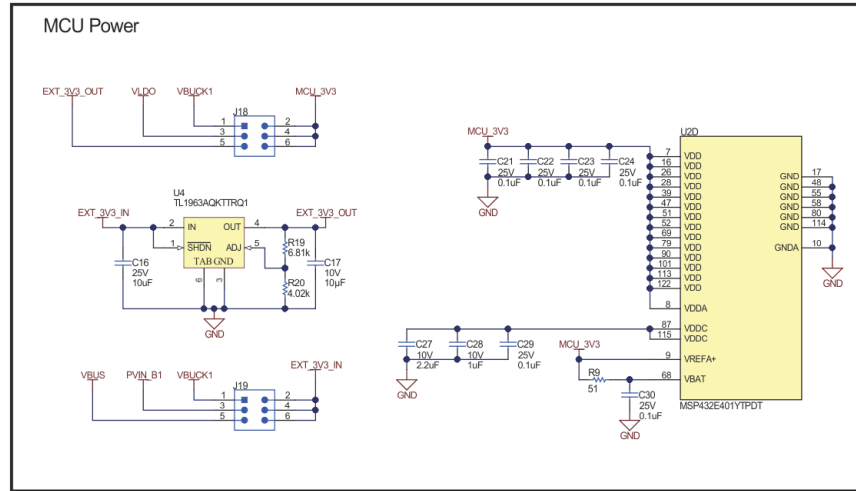
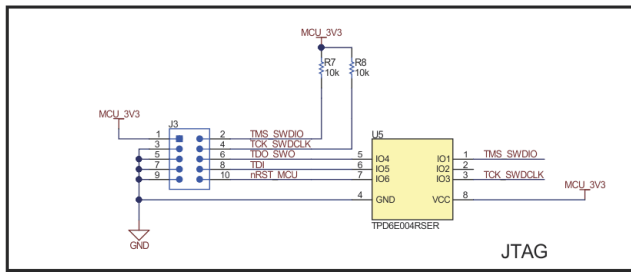
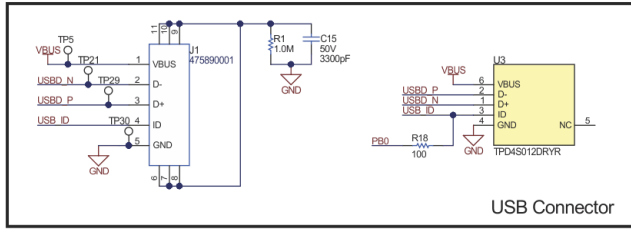
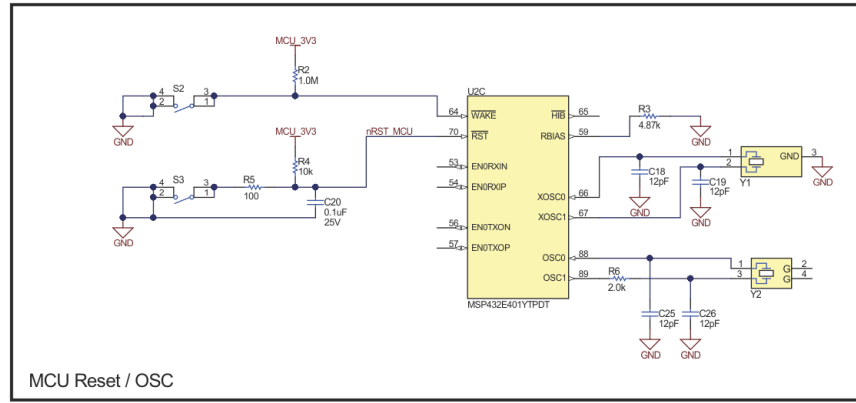
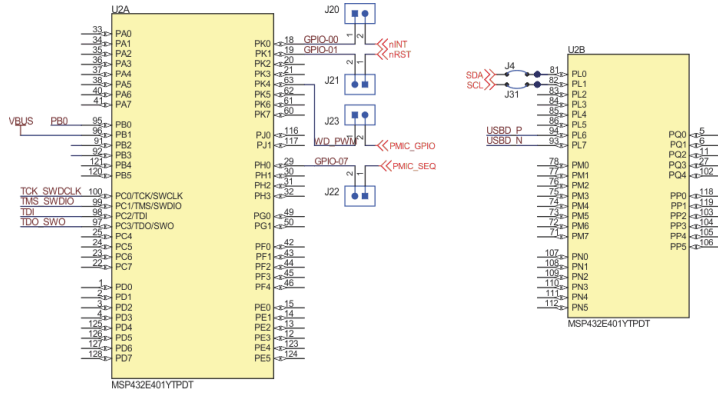


Figure 8-2. MSP432E401Y Schematic

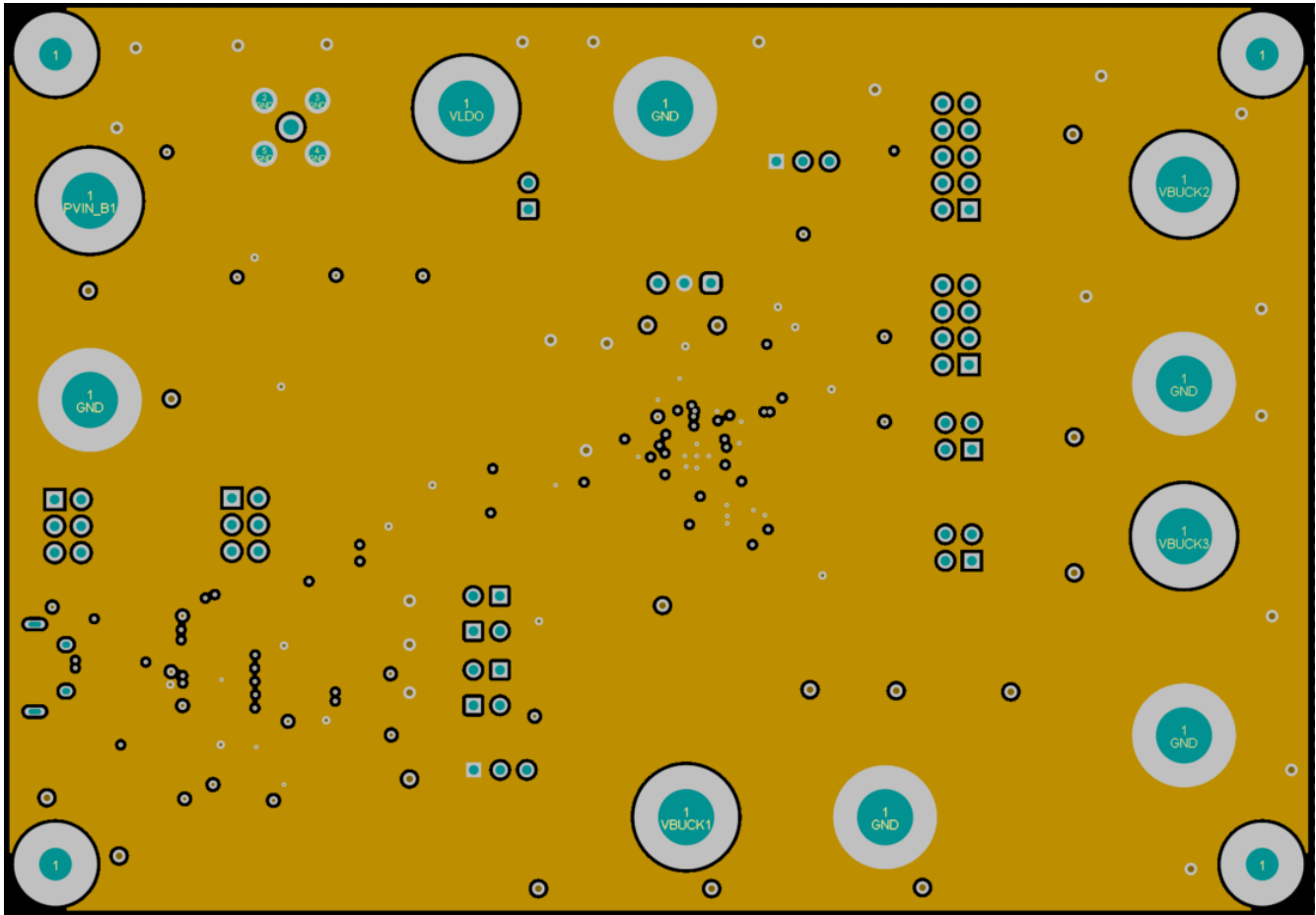


Figure 9-2. Mid-Layer 1

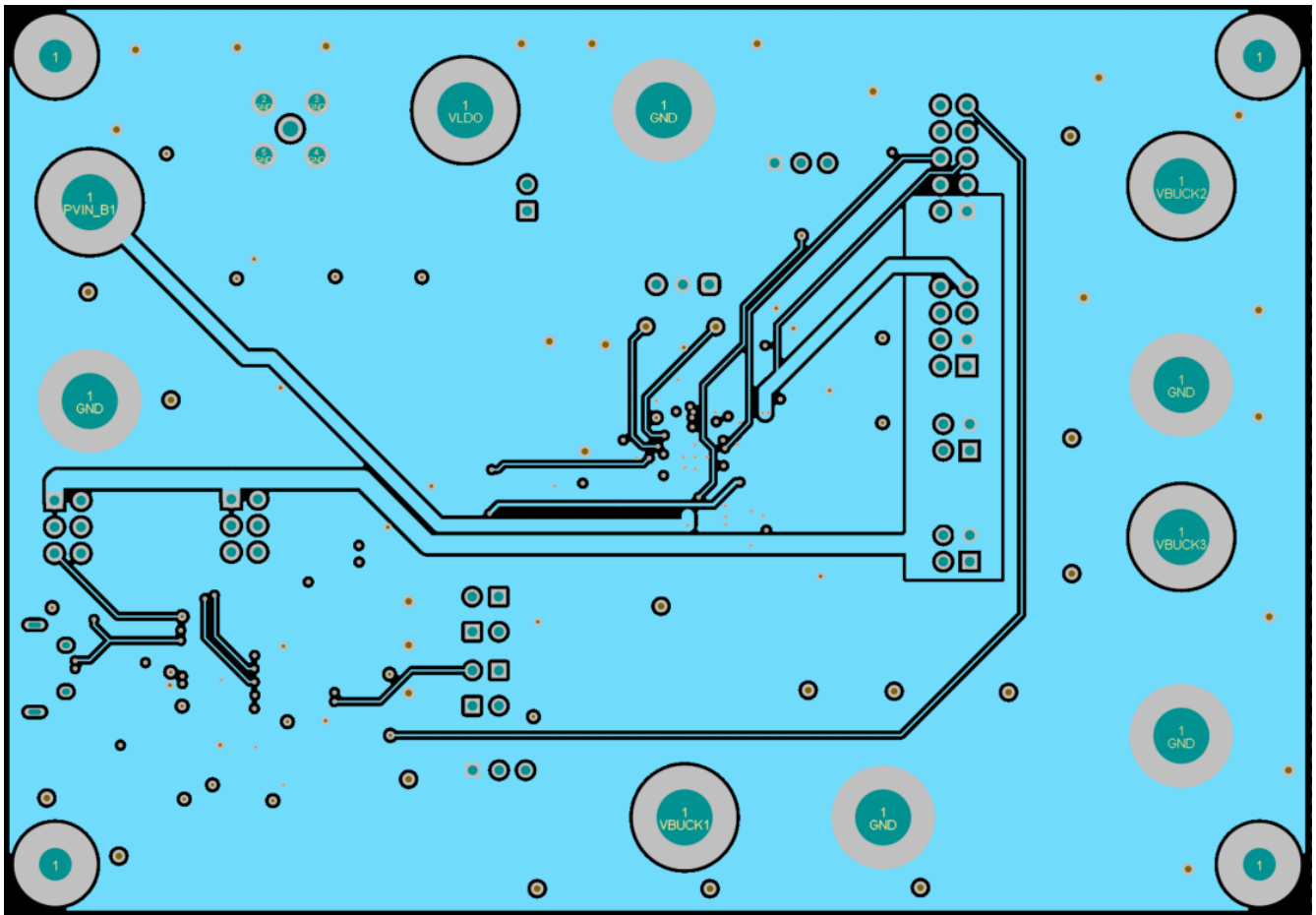


Figure 9-3. Mid-Layer 2

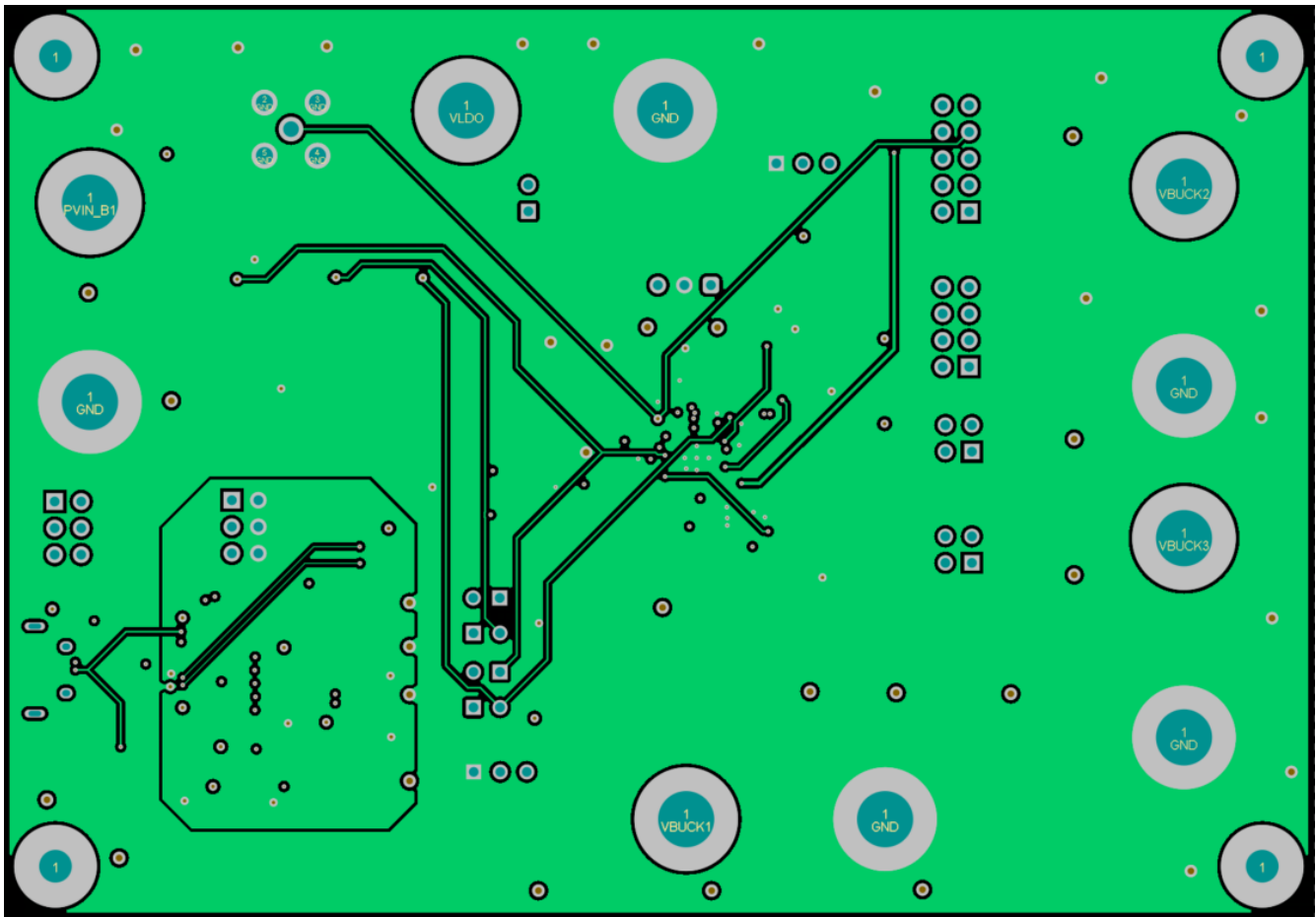


Figure 9-4. Mid-Layer 3

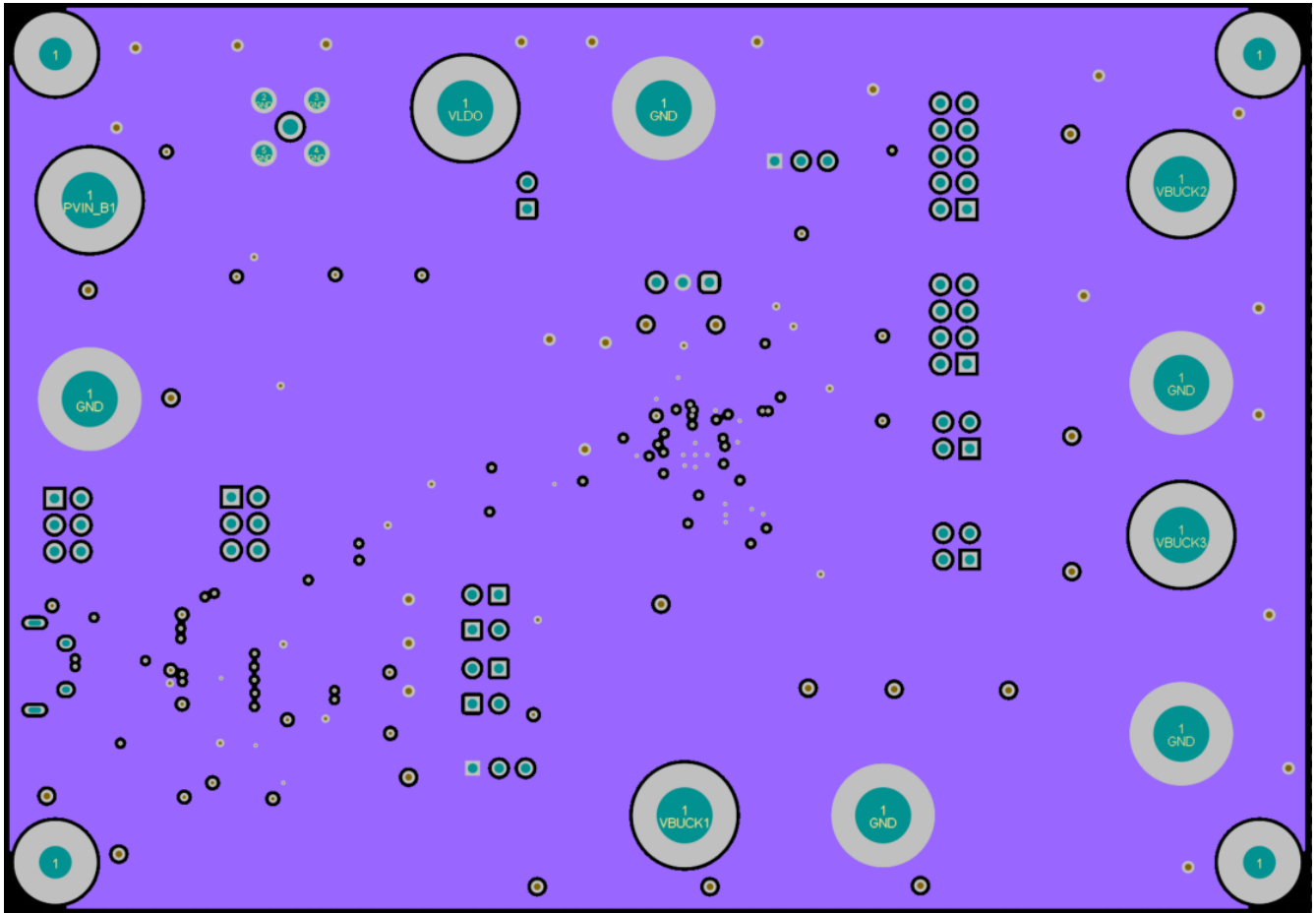


Figure 9-5. Mid-Layer 4

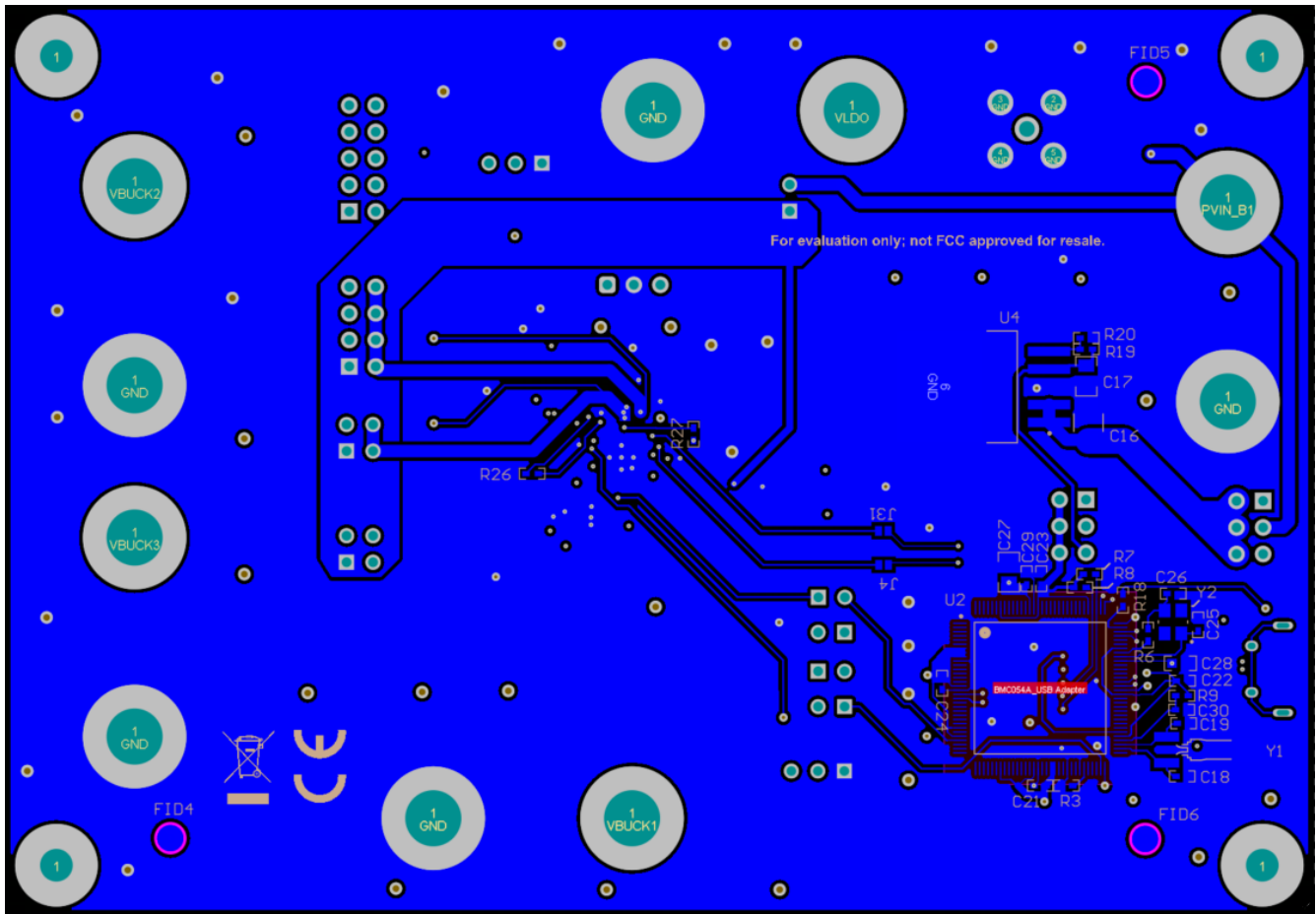


Figure 9-6. Bottom Layer (Mirrored)

10 TPS650330-Q1 EVM Bill of Materials

Table 10-1. TPS650330-Q1 EVM Bill of Materials

| Designator | Quantity | Value | Description | Package Reference | Part Number | Manufacturer |
|---|----------|-------------|---|-------------------------------------|----------------------|-----------------------------|
| !PCB1 | 1 | | Printed Circuit Board | | BMC054 | Any |
| C1 | 1 | 0.1 μ F | CAP, CERM, 0.1 μ F, 50 V, \pm 20%, X7R, AEC-Q200 Grade 1, 0402 | 0402 | CGA2B3X7R1H104M050BB | TDK |
| C2, C4, C5 | 3 | | 10 μ F \pm 10% 10V Ceramic Capacitor X7S 0805 (2012 Metric) | 0805 | CGA4J3X7S1A106K125AE | TDK |
| C3, C7 | 2 | 10 μ F | CAP, CERM, 10 μ F, 25 V, \pm 5%, X7R, AEC-Q200 Grade 1, 1206 | 1206 | C1206C106J3RACAUTO | Kemet |
| C8, C9 | 2 | 10 μ F | CAP, CERM, 10 μ F, 6.3 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0805 | 0805 | JMJ212CB7106KGHT | Taiyo Yuden |
| C10, C14, C28 | 3 | 1 μ F | CAP, CERM, 1 μ F, 10 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0603 | 0603 | LMK107B7105KAHT | Taiyo Yuden |
| C11, C12 | 2 | 2.2 μ F | CAP, CERM, 2.2 μ F, 6.3 V, \pm 10%, X7R, AEC-Q200 Grade 1, 0603 | 0603 | GCM188R70J225KE22D | MuRata |
| C15 | 1 | 3300 pF | CAP, CERM, 3300 pF, 50 V, \pm 10%, X7R, 0603 | 0603 | C0603C332K5RACTU | Kemet |
| C16 | 1 | 10 μ F | CAP, CERM, 10 μ F, 25 V, \pm 20%, X7R, AEC-Q200 Grade 1, 1210 | 1210 | CGA6P1X7R1E106M250AC | TDK |
| C17 | 1 | 10 μ F | CAP, CERM, 10 μ F, 10 V, \pm 5%, X7R, AEC-Q200 Grade 1, 0805 | 0805 | C0805C106J8RACAUTO | Kemet |
| C18, C19, C25, C26 | 4 | 12 pF | CAP, CERM, 12 pF, 50 V, \pm 5%, C0G/NP0, AEC-Q200 Grade 1, 0402 | 0402 | GCM1555C1H120JA16J | MuRata |
| C20, C21, C22, C23, C24, C29, C30 | 7 | 0.1 μ F | CAP, CERM, 0.1 μ F, 25 V, \pm 10%, X7R, 0402 | 0402 | GRM155R71E104KE14D | MuRata |
| C27 | 1 | 2.2 μ F | CAP, CERM, 2.2 μ F, 10 V, \pm 10%, X7R, 0805 | 0805 | C0805C225K8RACTU | Kemet |
| D3, D4, D5 | 3 | Green | LED, Green, SMD | 1.7x0.65x0.8 mm | LG L29K-G2J1-24-Z | OSRAM |
| H1, H2, H3, H4 | 4 | | Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead | Screw | NY PMS 440 0025 PH | B&F Fastener Supply |
| H5, H6, H7, H8 | 4 | | Standoff, Hex, 0.5 in L #4-40 Nylon | Standoff | 1902C | Keystone |
| J1 | 1 | | Connector, Receptacle, Micro-USB Type AB, R/A, Bottom Mount SMT | 5.6x2.5x8.2 mm | 475890001 | Molex |
| J2, J4, J5, J6, J7, J29, J31 | 7 | | Jumper, SMT | shorting jumper, SMT | JMP-36-30X40SMT | Any |
| J3 | 1 | | Header (Shrouded), 1.27 mm, 5x2, Gold, SMT | Header(Shrouded), 1.27 mm, 5x2, SMT | FTSH-105-01-F-DV-K | Samtec |
| J8 | 1 | | Header, 100 mil, 5x2, Tin, TH | Header, 5x2, 100 mil, Tin | PEC05DAAN | Sullins Connector Solutions |
| J9, J10, J11, J12, J13, J14, J25, J26, J27, J28 | 10 | | Standard Banana Jack, Uninsulated, 8.9 mm | Keystone575-8 | 575-8 | Keystone |
| J15, J16 | 2 | | Header, 100 mil, 2x2, Tin, TH | Header, 2x2, 2.54 mm, TH | PEC02DAAN | Sullins Connector Solutions |

Table 10-1. TPS650330-Q1 EVM Bill of Materials (continued)

| Designator | Quantity | Value | Description | Package Reference | Part Number | Manufacturer |
|-------------------------|----------|-------------|--|--------------------------------|----------------------|-----------------------------|
| J17 | 1 | | Header, 100 mil, 4x2, Tin, TH | Header, 4x2, 100mil, Tin | PEC04DAAN | Sullins Connector Solutions |
| J18, J19 | 2 | | Header, 100 mil, 3x2, Tin, TH | 3x2 Header | PEC03DAAN | Sullins Connector Solutions |
| J20, J21, J22, J23, J33 | 5 | | Header, 100 mil, 2x1, Tin, TH | Header, 2 PIN, 100 mil, Tin | PEC02SAAN | Sullins Connector Solutions |
| J24, J34 | 2 | | Header, 100 mil, 2x1, Tin, SMD | SMD, 2-Leads, Body 200x100 mil | TSM-102-01-T-SV-P-TR | Samtec |
| J30 | 1 | | Connector, SMA, TH | SMA | 142-0701-201 | Cinch Connectivity |
| J35 | 1 | | Header, 100 mil, 3x1, Gold, TH | 3x1 Header | TSW-103-07-G-S | Samtec |
| L1 | 1 | 1.5 μ H | Inductor, Shielded, Metal Composite, 1.5 μ H, 2.3 A, 0.11 Ω , AEC-Q200 Grade 0, SMD | 0806 | TFM201610ALMA1R5 MTA | TDK |
| L2, L3 | 2 | 1 μ H | Inductor, Shielded, Metal Composite, 1 μ H, 3.1 A, 0.06 Ω , AEC-Q200 Grade 0, SMD | 0806 | TFM201610ALMA1R0 MTA | TDK |
| LBL1 | 1 | | Thermal Transfer Printable Labels, 0.650 in W x 0.200 in H - 10,000 per roll | PCB Label 0.650 x 0.200 in | THT-14-423-10 | Brady |
| Q1, Q2, Q3 | 3 | 25 V | MOSFET, N-CH, 25 V, 5 A, DQK0006C (WSON-6) | DQK0006C | CSD16301Q2 | Texas Instruments |
| R1, R22, R23, R24 | 4 | 1.0 Meg | RES, 1.0 M, 5%, 0.1 W, AEC-Q200 Grade 0, 0603 | 0603 | CRCW06031M00JNEA | Vishay-Dale |
| R2 | 1 | 1.0 Meg | RES, 1.0 M, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04021M00JNED | Vishay-Dale |
| R3 | 1 | 4.87 k | RES, 4.87 k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04024K87FKED | Vishay-Dale |
| R4, R7, R8 | 3 | 10 k | RES, 10 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW040210K0JNED | Vishay-Dale |
| R5, R18 | 2 | 100 | RES, 100, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW0402100RJNED | Vishay-Dale |
| R6 | 1 | 2.0 k | RES, 2.0 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04022K00JNED | Vishay-Dale |
| R9 | 1 | 51 | RES, 51, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW040251R0JNED | Vishay-Dale |
| R10, R13 | 2 | 1.0 k | RES, 1.0 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04021K00JNED | Vishay-Dale |
| R11, R12, R21 | 3 | 330 | RES, 330, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW0402330RJNED | Vishay-Dale |
| R14 | 1 | 100 k | RES, 100 k, 5%, 0.1 W, AEC-Q200 Grade 0, 0402 | 0402 | ERJ-2GEJ104X | Panasonic |
| R15, R16, R17, R26, R27 | 5 | 0 | RES, 0, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04020000Z0ED | Vishay-Dale |
| R19 | 1 | 6.81 k | RES, 6.81 k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04026K81FKED | Vishay-Dale |
| R20 | 1 | 4.02 k | RES, 4.02 k, 1%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW04024K02FKED | Vishay-Dale |
| R25 | 1 | 47 k | RES, 47 k, 5%, 0.063 W, AEC-Q200 Grade 0, 0402 | 0402 | CRCW040247K0JNED | Vishay-Dale |
| S1, S4 | 2 | | Switch, Slide, SPDT, On-Off-On, 3 Pos, 0.05 A, 48 V, TH | 9.5x5 mm | AS1E-2M-10-Z | Copal Electronics |

Table 10-1. TPS650330-Q1 EVM Bill of Materials (continued)

| Designator | Quantity | Value | Description | Package Reference | Part Number | Manufacturer |
|---|----------|-------|---|------------------------------|----------------------------|-----------------------------|
| S2, S3 | 2 | | Switch, SPST, Off-Mom, 0.05 A, 12 VDC, SMD | 3.5x2.9 mm | 434153017835 | Würth Elektronik |
| SH-J1, SH-J2, SH-J3, SH-J4, SH-J5, SH-J6, SH-J7, SH-J8, SH-J9 | 9 | 1x2 | Shunt, 100 mil, Flash Gold, Black | Closed Top 100 mil Shunt | SPC02SYAN | Sullins Connector Solutions |
| TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20, TP21, TP22, TP23, TP24, TP25, TP26, TP27, TP28, TP29, TP30 | 30 | | Test Point, Miniature, SMT | Testpoint_Keystone_Miniature | 5015 | Keystone |
| U1 | 1 | | Highly integrated power management IC for automotive camera modules | VQFN24 | TPS650330QRGEQ1 | Texas Instruments |
| U2 | 1 | | MSP432E401YTPDT, PDT0128A (TQFP-128) | PDT0128A | MSP432E401YTPDT | Texas Instruments |
| U3 | 1 | | USB ESD Solution with Power Clamp, 4 Channels, -40 to +85 °C, 6-pin SON (DRY), Green (RoHS & no Sb/Br) | DRY0006A | TPD4S012DRYR | Texas Instruments |
| U4 | 1 | | Single Output Fast Transient Response LDO, 1.5 A, Adjustable 1.21 to 20 V Output, 2.1 to 20 V Input, 5-pin DDPK (KTT), -40 to 125 °C, Green (RoHS & no Sb/Br) | KTT0005A | TL1963AQKTRRQ1 | Texas Instruments |
| U5 | 1 | | Low-Capacitance 6-Channel ±15 kV ESD Protection Array for High-Speed Data Interfaces, RSE0008A (UQFN-8) | RSE0008A | TPD6E004RSER | Texas Instruments |
| Y1 | 1 | | Crystal, 32.768 kHz, SMD | D1.9xL6 mm | CMR200T-32.768KDZ Y-UT | Citizen FineDevice |
| Y2 | 1 | | Crystal, 25 MHz, 8pF, SMD | 3.2x0.75x2.5 mm | NX3225GA-25.000M-STD-CRG-2 | NDK |
| C6 | 0 | 10 µF | CAP, CERM, 10 µF, 25 V, ± 5%, X7R, AEC-Q200 Grade 1, 1206 | 1206 | C1206C106J3RACAU TO | Kemet |
| C13 | 0 | 1 µF | CAP, CERM, 1 µF, 10 V, ± 10%, X7R, AEC-Q200 Grade 1, 0603 | 0603 | LMK107B7105KAHT | Taiyo Yuden |

11 TPS650330-Q1 Silicon Revision Changes

The final silicon revision for the TPS65033x-Q1 family of PMICs is denoted *B0*. This corresponds to die revision PG 2.0. [Table 11-1](#) lists the feature changes compared to the first revision of silicon, *A0* or PG 1.0.

Table 11-1. TPS65033x-Q1 Silicon Revision B0 Feature Changes

| Item | Design Block | Parameter Impacted | Silicon Revision A0 | Silicon Revision B0 | Details |
|------|--------------|----------------------------|---|--|---|
| 1 | BUCK1 | Output Voltage Settings | 3.0 V to 4.0 V | 2.5 V to 4.0 V | Maintains 50 mV increments |
| 2 | LDO | Output Voltage Settings | 2.7 V to 3.3 V | 1.8 V, 2.5 V to 3.3 V | 1.8 V and 1.825 V settings 2.5 V to 3.2 V settings in 25 mV increments 3.3 V setting |
| 3 | BUCK1 | PVIN_B1_UVLO | Rising threshold only | Rising and Falling thresholds | Same threshold settings as Rising thresholds with a 4% hysteresis delta between rising and falling |
| 4 | Digital | Warm Threshold | Exceeding Warm Threshold will keep State Machine from transitioning to the Active state | Option to allow the State Machine to transition to the Active State if the Warm Threshold is exceeded | User programmable in pre-production devices. Factory programmable in production devices. |
| 5 | Digital | LDO Pre-Bias Condition | Not applicable | Option to allow the LDO to power on into a pre-bias condition | User programmable in pre-production devices. Factory programmable in production devices. |
| 6 | Digital | I2C Bus | Always enabled | Option to disable | Factory programmable only |
| 7 | Digital | Configuration CRC | Can be disabled by the user during the configuration process | Can be disabled by the user during the configuration process and programmed to remain disabled | User programmable in pre-production devices. Factory programmable in production devices. |
| 8 | Digital | State Transition Control | Not applicable | Option to define the state transition for Priority 2 Faults (either the Reset State or Wait Power Cycle State) | User programmable in pre-production devices. Factory programmable in production devices. Does not apply to the TPS650331-Q1 device. |
| 9 | Digital | ABIST Run Time Control | ABIST only runs on power up | ABIST runs on power up or whenever commanded to run | Option is factory programmable only |
| 10 | Digital | SEQ Pin Latch | Not applicable | Option to latch the state of the SEQ pin in order to perform a complete power up or power down sequence | Option is factory programmable only |
| 11 | Digital | Power Good Status Register | Not applicable | Register bits added to provide the power good status of BUCK1, BUCK2, BUCK3, and the LDO. Status bits also added for nRSTOUT, GPIO, and SEQ pins | Read only register |

12 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision * (February 2020) to Revision A (October 2020) | Page |
|--|-------------|
| • Updated the numbering format for tables, figures, and cross-references throughout the document..... | 1 |
| • Deleted the Hot Surface Warning..... | 3 |
| • Changed the EVM images to EVM Revision A..... | 3 |
| • Removed the J23 Jumper and GPIO PMIC Pin from the <i>Adapter PMIC Connections</i> table..... | 3 |
| • Changed the EVM defaults for all regulators..... | 4 |
| • Updated the current limiting feature specifications in the <i>Low Noise LDO Features</i> table..... | 5 |
| • Updated the output discharge configurable range in the <i>Low Noise LDO Configurable Settings</i> table..... | 5 |
| • Changed the EVM Configurations..... | 6 |
| • Updated the <i>TPS650330-Q1 EVM Test Points</i> table..... | 7 |
| • Updated the <i>Graphical User Interface</i> section..... | 8 |
| • Updated the <i>I²C Communication Port and Adapter Debugging</i> section..... | 10 |
| • Added the <i>TPS650330-Q1 EVM Schematic</i> section..... | 21 |
| • Added the <i>TPS650330-Q1 EVM PCB Layers</i> section..... | 23 |
| • Added the <i>TPS650330-Q1 EVM Bill of Materials</i> section..... | 29 |
| • Added the <i>TPS650330-Q1 Silicon Revision Changes</i> section..... | 32 |

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